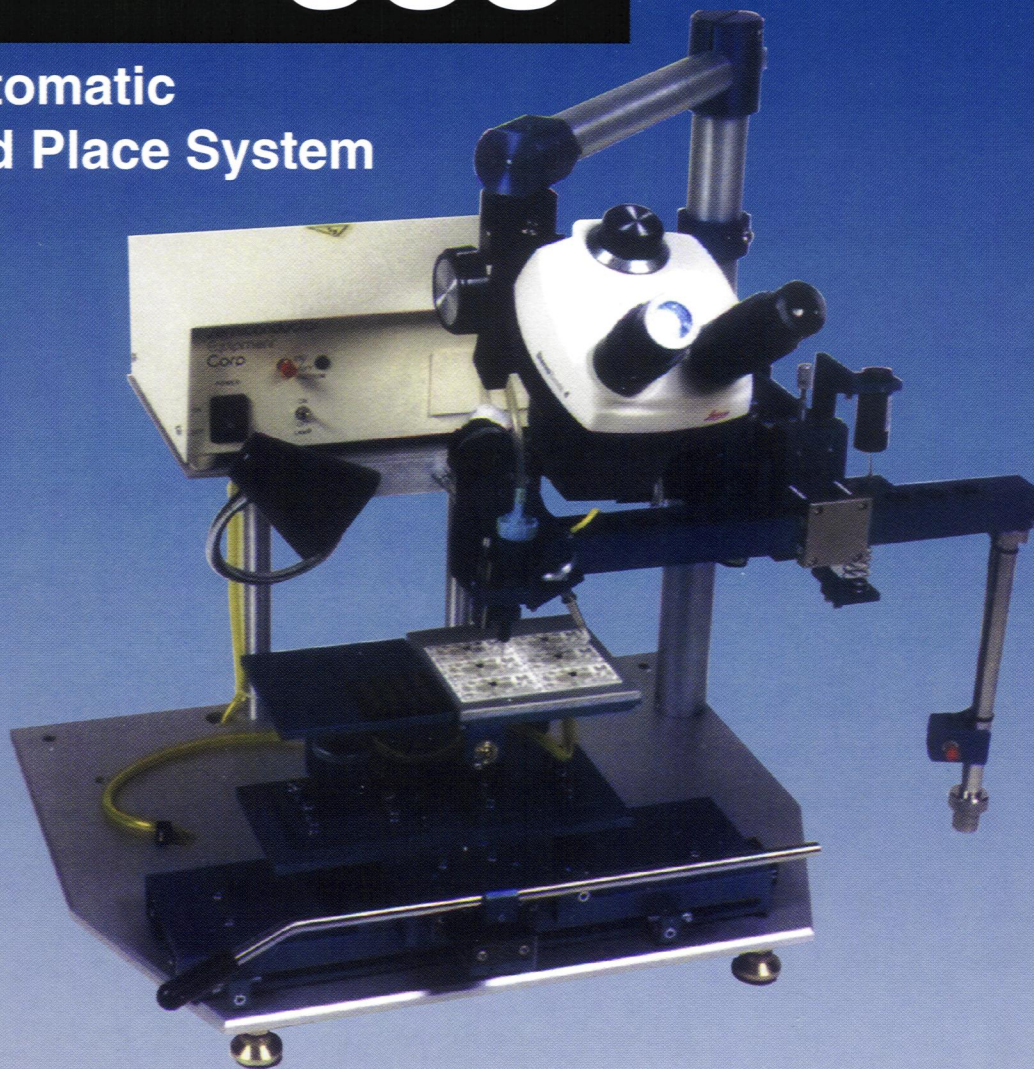


Model 830

NEW

Semiautomatic Pick and Place System



Semiconductor Equipment Corporation's Model 830 is a general purpose pick and place system for die and surface mount components. The 830 offers manually or pneumatically controlled Z motion with semiautomatic vacuum pickup tool movement for transferring die and other small devices from tape or carrier trays to packages. A footswitch option controls the pick-up head to lower the pickup tool to working height and return it home. Open frame design assures full visibility and complete access of all system components. Operator friendly—takes less than two minutes to learn to operate. Epoxy die bonding capability can be easily added. The 830 works with any tape-mounted die removal system, including S.E.C.'s Model 4750 poker pin type die ejector featuring a choice of pin patterns or S.E.C.'s Model 4800 heated tape expanding die ejector grid featuring a grid plate that can be machined with one of two different pyramid pitches.



Moorpark, California U.S.A.

Model 830

Control module with all necessary electronic and pneumatic logic for operating specified attachments.

High intensity illuminators (optional).

Dual position pivoting head for epoxy dispensing (optional).

Die tray pedestal capable of holding up to four 2" X 2" waffle packs (optional).

Stereo zoom microscope and/or projected image cross hair system (optional).

Flat vacuum chuck capable of holding up to four 2" X 2" waffle packs (optional).

Manual Z motion with drop down control knob for die tool rotation. Semiautomatic Z motion (optional).

Manual X-Y precision slide table with 6" X 12" (or 9" X 15") of travel.

SPECIFICATIONS:

- Plus or minus 25 micron placement accuracy.
- Four 2" X 2" waffle pack pickup stage available.
- Four inch square vacuum stage standard (optional sizes available).
- Consistent bond load.
- Throughput—up to 400 placements per hour.

Dimensions: 26" W X 18" D X 18" H

Weight: 35 lbs

Power: 120 VAC 1 amp or 220 VAC 1 amp

Vacuum: 20" Hg



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